



SOT848-3

HLQFP128, plastic, thermal enhanced low profile quad flat package; 128 terminals; 0.5 mm pitch; 14 mm x 20 mm x 1.4 mm body

16 September 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP128
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-03-2017
Manufacturer package code	98ASA01050D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	20	-	mm
package width	-	14	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	128	-	



HLQFP128, plastic, thermal enhanced low profile quad flat package; 128 terminals; 0.5 mm pitch; 14 mm x 20 mm x 1.4 mm body

2 Package outline

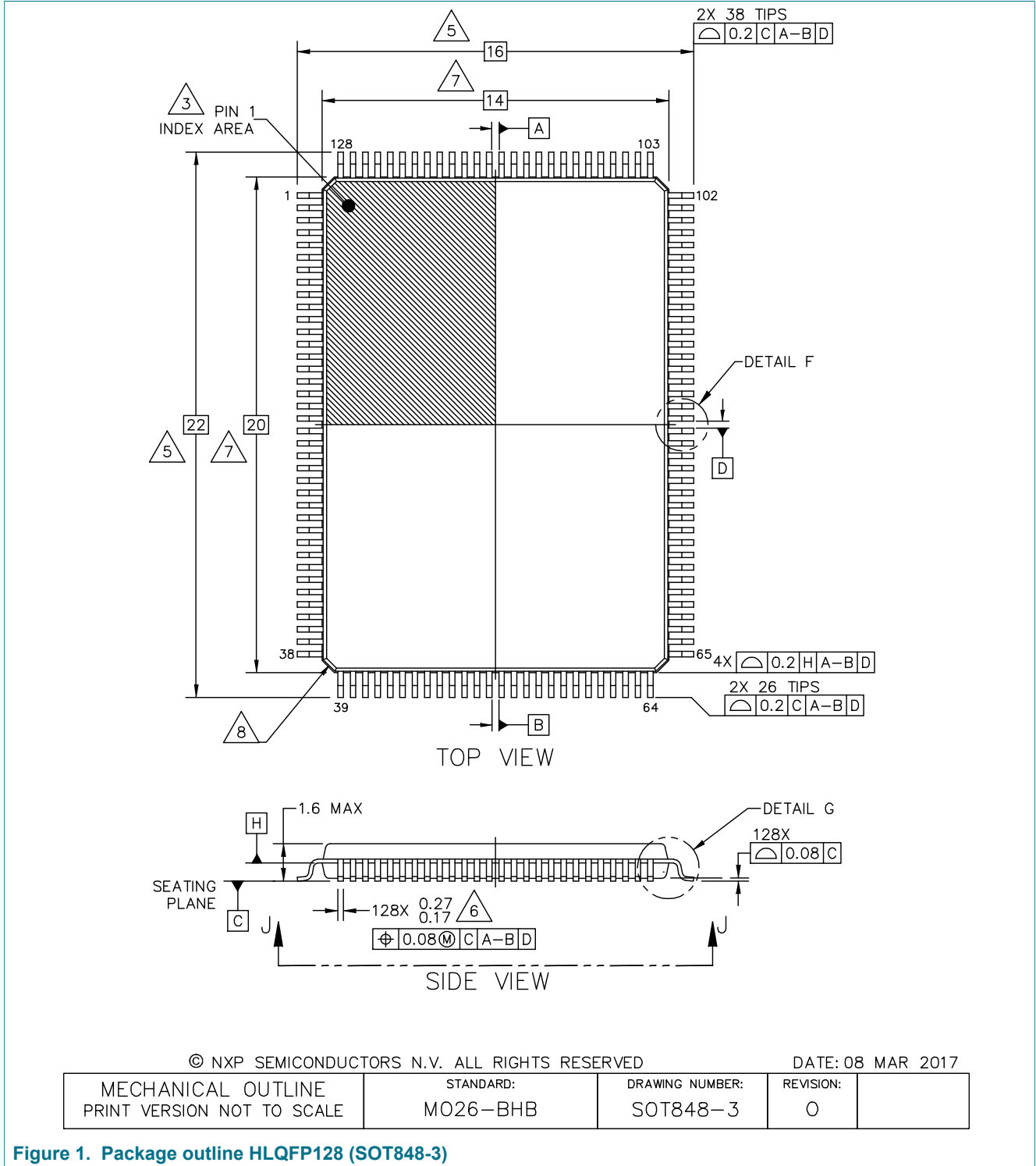


Figure 1. Package outline HLQFP128 (SOT848-3)

HLQFP128, plastic, thermal enhanced low profile quad flat package; 128 terminals; 0.5 mm pitch; 14 mm x 20 mm x 1.4 mm body

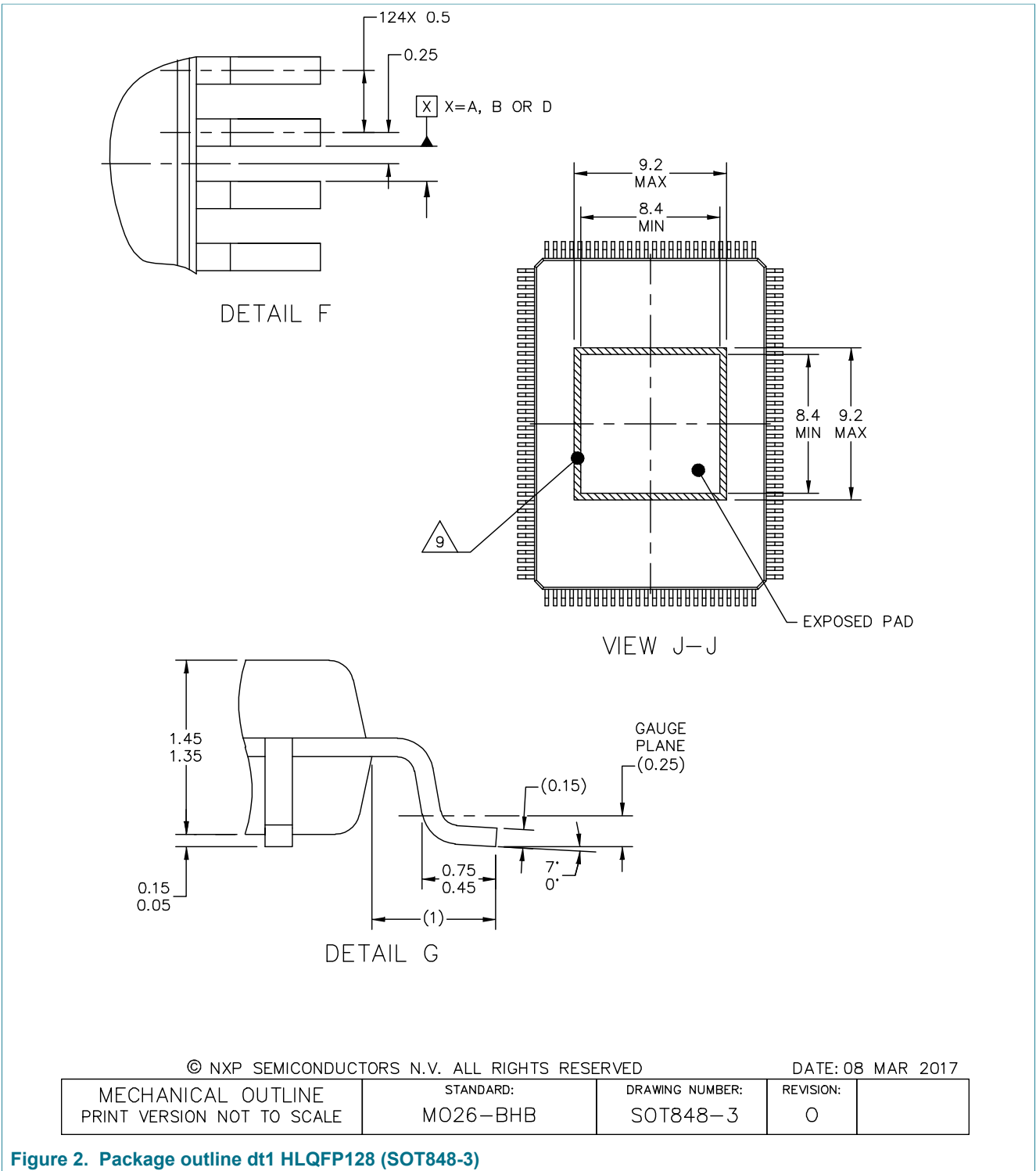


Figure 2. Package outline dt1 HLQFP128 (SOT848-3)

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 CONFIGURATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 08 MAR 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO26-BHB	DRAWING NUMBER: SOT848-3	REVISION: 0	
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Figure 3. Package outline note HLQFP128 (SOT848-3)

3 Legal information

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